



Final Product Change Notification

201708003F02

Issue Date: 01-Dec-2017

Effective Date: 15-Dec-2017

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QUALITY

Management Summary

Assembly transfer of the MMA865x family from Amkor Korea (ATK1) to ASE-Chungli Taiwan (ASECL) assembly site for continuous customer supply.

Change Category

☐ Wafer Fab Process	☒ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☒ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☒ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage

MMA865x ASECL
Transfer and Copper
Wire Qualification

Details of this Change

NXP Semiconductors announces the completion of the consumer level qualification of the ASE-Chungli Taiwan (ASECL) assembled MMA8652FCR1 and MMA8653FCR1 products.

NXP Semiconductors ASE-Chungli Taiwan (ASECL) assembled MMA8652 and MMA8653 products are qualified with the materials change to Gold Palladium Copper (AuPdCu) wire, Sumitomo EME-G700LA mold compound and Ablestik die attach film ATB-125/ATB-125HA2. These products were previously assembled with Gold (Au) wire, Sumitomo EME-G700 mold compound, and Henkel ATB-120A DAF die attach material.

Reliability qualification and full electrical characterization over temperature has been completed. There is no change to thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (within specification and with no changes to distributions).

Why do we Implement this Change

The transfer to ASECL is for supply continuity as a result of ATK1 closure. The transfer from Gold to Gold Palladium Copper wire is an alignment to industry standard convention for wirebond material type. The

change to mold compound and die attach material for DFN 2x2 package is required to standardize the bill of materials for ASECL assembly production.

Identification of Affected Products

Product identification does not change

There is no change to the orderable part numbers. NXP will have traceability of the assembly site by the 2nd digit of the tracecode.

Product Availability

Sample Information

Samples are available from 12-Aug-2017

Samples available for MMA8652 and MMA8653 with special marking for customer evaluation.

Production

Planned first shipment 30-Oct-2017

Impact

no impact to the product's functionality anticipated.

No impact to product form, fit, function or reliability.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 31-Dec-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Sok Ching Kim Bosiwang Wang

Position Product Engineer

e-mail address kimwang@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
MMA8653FCR1	935317374115	MMA8653FCR1	3-axis 2g/4g/8g 10 bit	VSON10	RFS	BL Sensors
MMA8652FCR1	935310642115	MMA8652FCR1	3-axis 2g/4g/8g 12 bit	VSON10	RFS	BL Sensors